

Polymer PTC Devices

Surface mount fuses

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LP-USM075

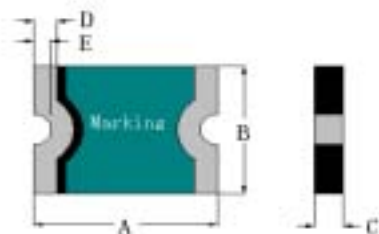
Features

- Smaller size of 1210
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

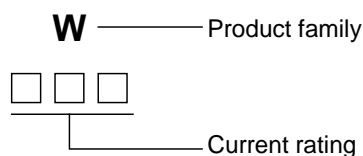


Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-USM075	3.43	2.80	1.30	0.60	0.20



Part Marking System



Electrical Characteristics

Part number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} Current(A) Time(S)	$P_{d\ typ}$ (W)	R_{min} (Ω)	$R_{1\ max}$ (Ω)
LP-USM075	0.75	1.50	6	40	8.0 0.10		0.13	0.40

I_H =Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T =Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

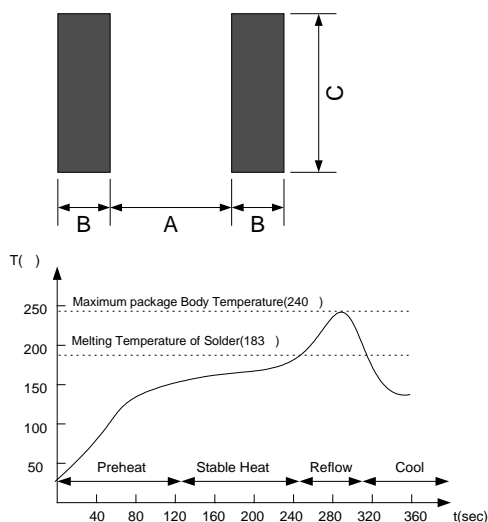
T_{trip} =Maximum time to trip(s) at assigned current.

$P_{d\ typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25 °C prior to tripping.

$R_{1\ max}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-USM075	2.00	1.00	2.50

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.